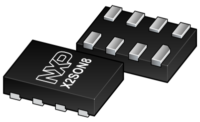


SOT1986-1

X2SON8, super thin small outline package, no leads; 8 terminals; 0.35 mm pitch; 1.4 mm x 1.0 mm x 0.32 mm body

6 September 2018

Package information

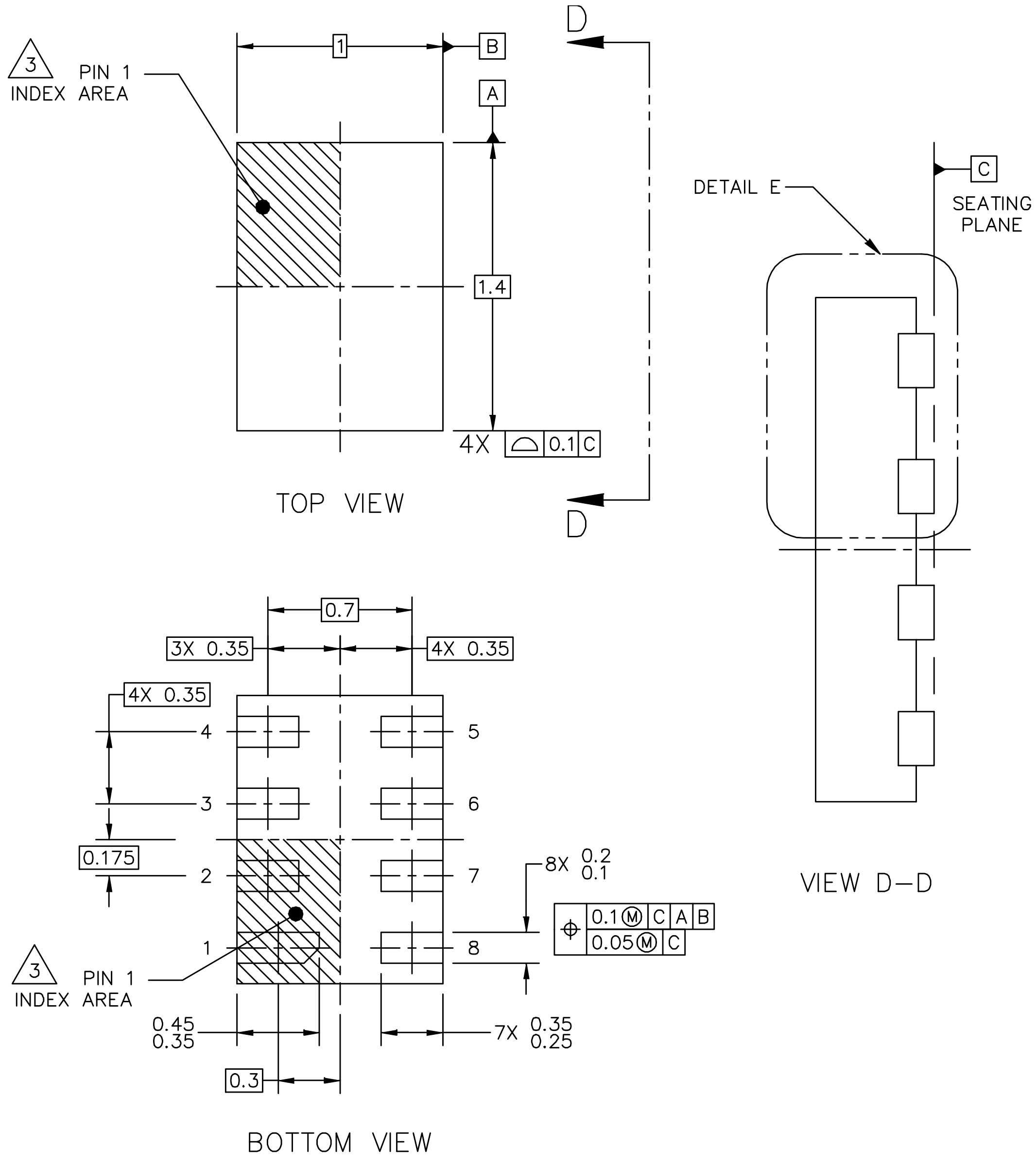
1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	X2SON8
Package style descriptive code	XSON (extremely thin small outline; no leads)
Mounting method type	S (surface mount)
Issue date	06-08-2018
Manufacturer package code	98ASA01287D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	1.4	-	mm
package width	-	1	-	mm
seated height	-	0.32	-	mm
nominal pitch	-	0.35	-	mm
actual quantity of termination	-	8	-	

2 Package outline



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MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01287D	REVISION: 0	

Figure 1. Package outline X2SON8 (SOT1986-1)

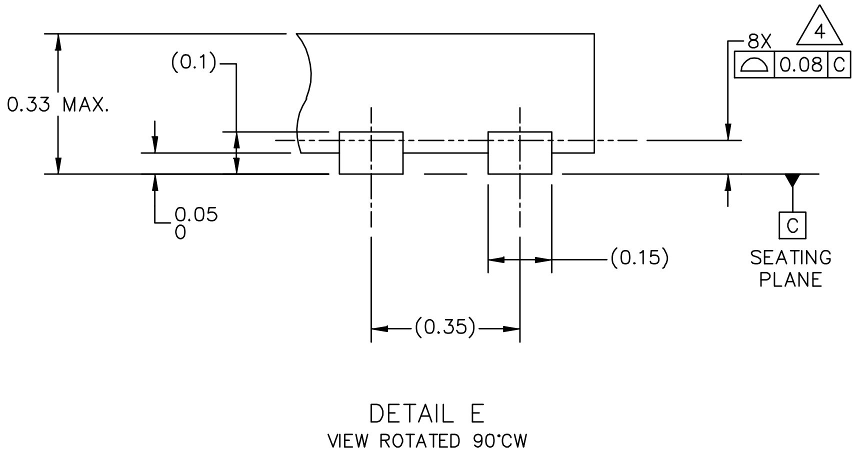

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Figure 2. Package outline detail X2SON8 (SOT1986-1)

3 Soldering

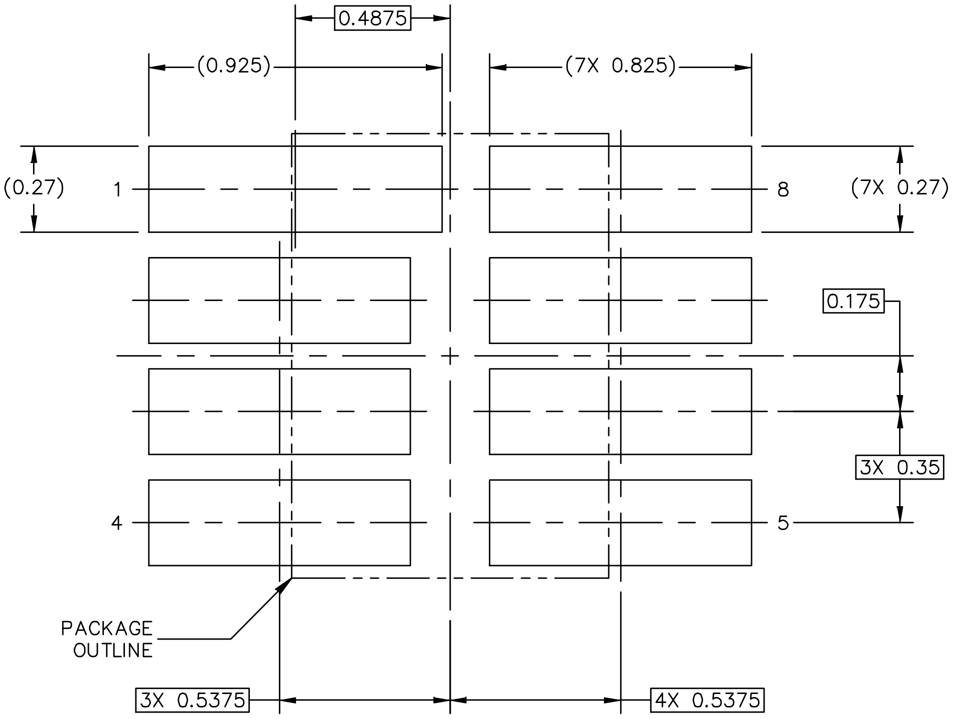

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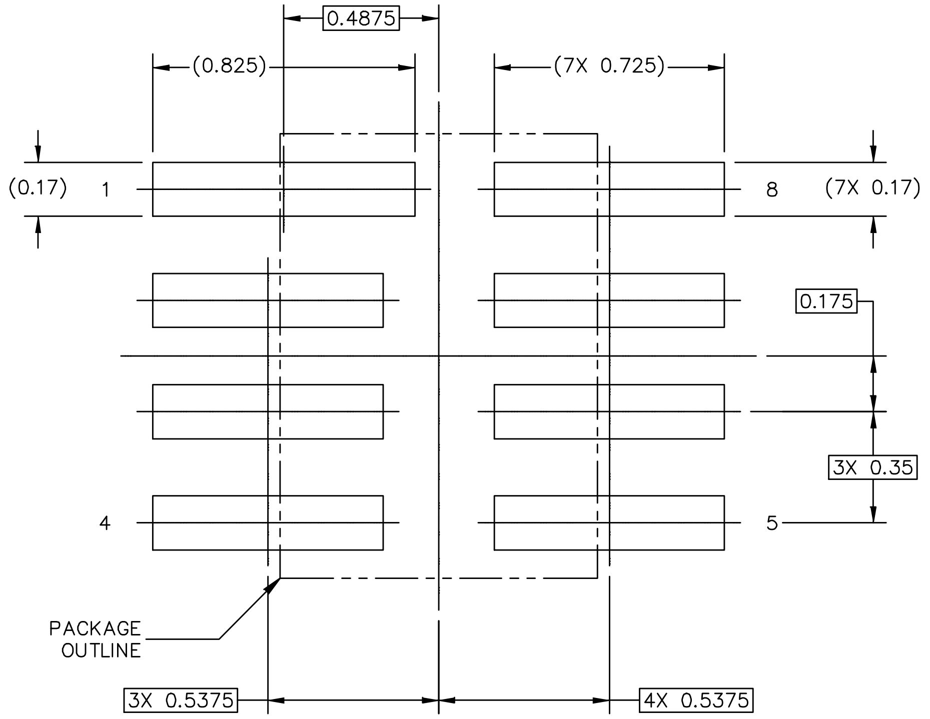
Figure 3. Reflow soldering footprint part1 for X2SON8 (SOT1986-1)



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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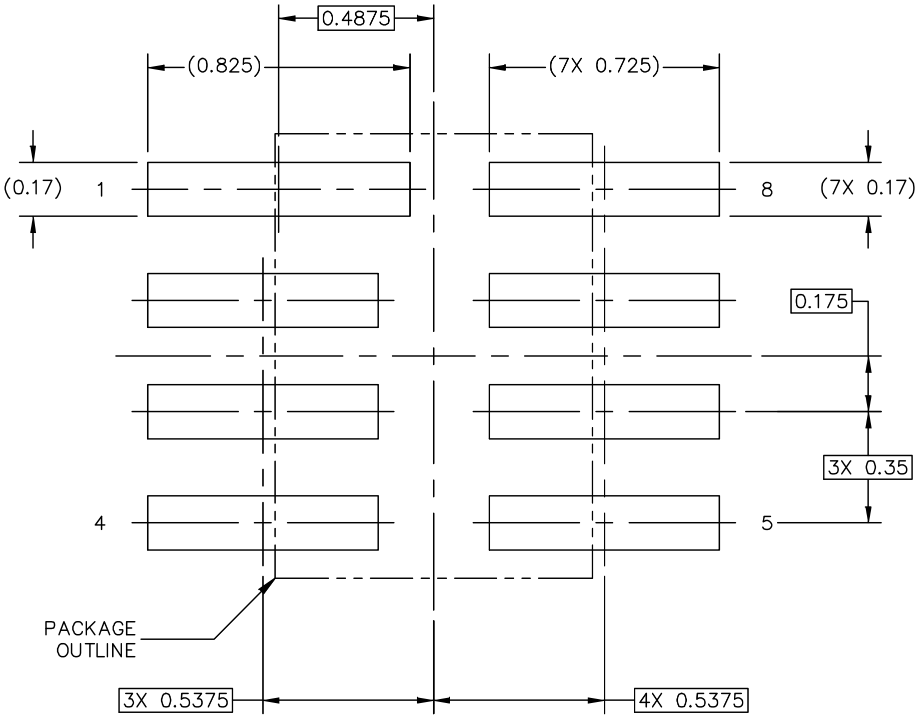
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01287D	REVISION: O	

Figure 4. Reflow soldering footprint part2 for X2SON8 (SOT1986-1)



STENCIL THICKNESS 0.1

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 5. Reflow soldering footprint part3 for X2SON8 (SOT1986-1)

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M−1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS.

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MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01287D	REVISION: O	

Figure 6. Package outline note X2SON8 (SOT1986-1)

4 Legal information

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